

Specification of Thermoelectric Module

TEHC1-127010

Description

The 127 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74 °C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Application

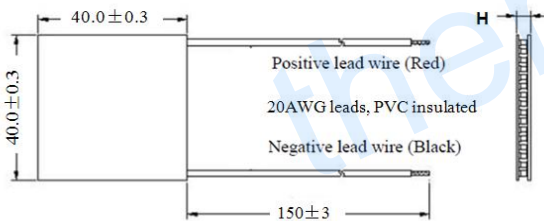
- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	16.8	18.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	1.6	1.6	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	16.7	18.0	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	8.2	8.8	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters

Manufacturing Options



A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

B. Sealant:

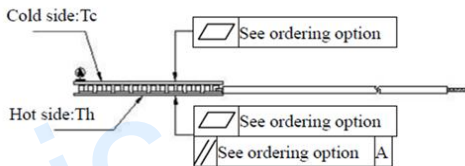
1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

C. Ceramics:

1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

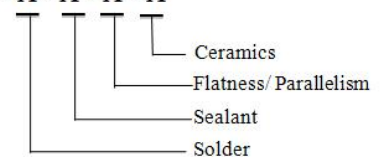


Ordering Option

Naming for the Module

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:7.1±0.1	0:0.08/0.08	150±3/Specify
TF	1:7.1±0.03	1:0.03/0.03	150±3/Specify
Eg. TF01: Thickness 7.1±0.1(mm) and Flatness 0.03/0.03(mm)			

TEHC1- 127010- X - X - X - X



TEHC1- 127010- T100 -SS - TF01- A1O

T100: Solder, BiSn (Melting Point=138 °C)

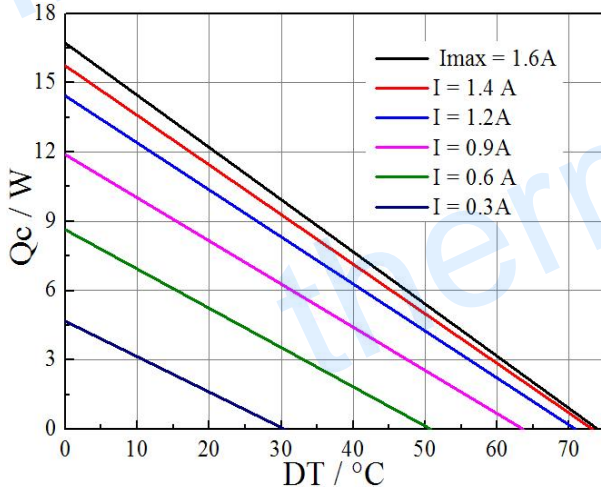
SS: Silicone sealing

A1O: Alumina white 96%

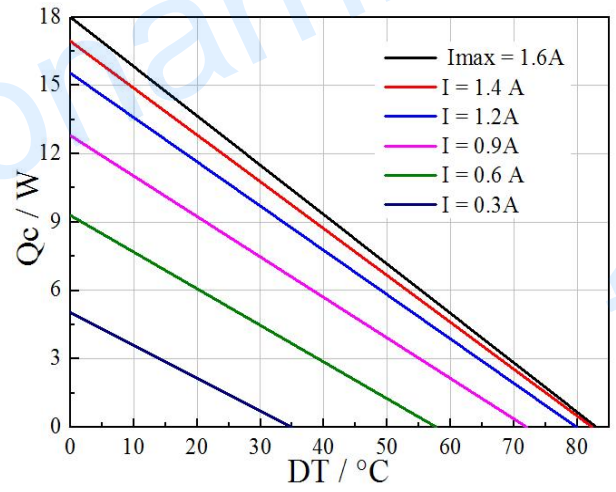
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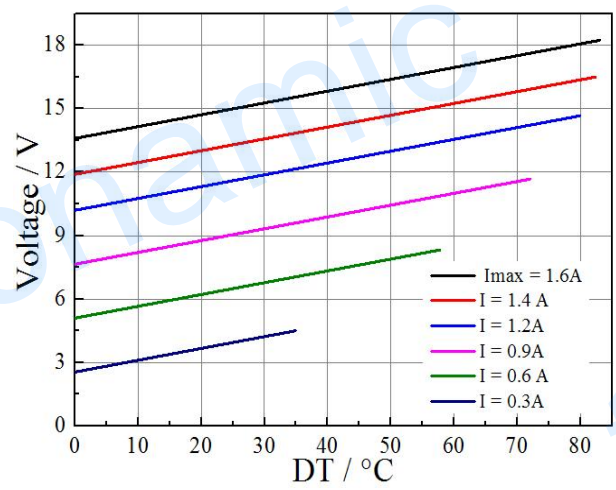
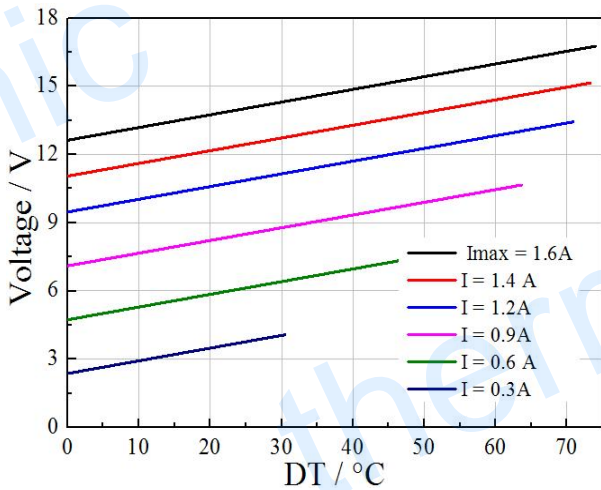
Performance Curves at Th=27 °C



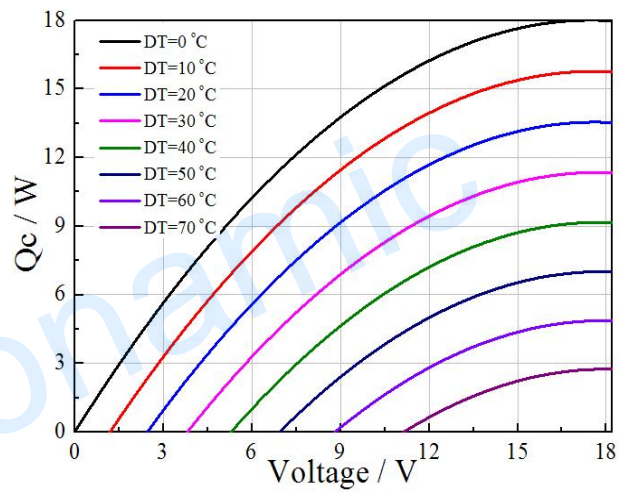
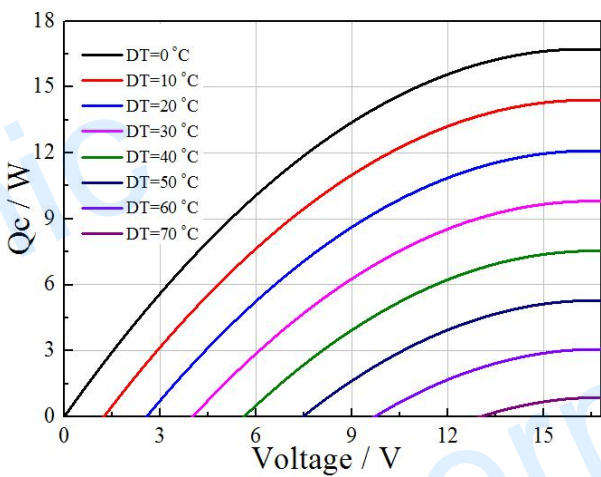
Performance Curves at Th=50 °C



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(\Delta T)$

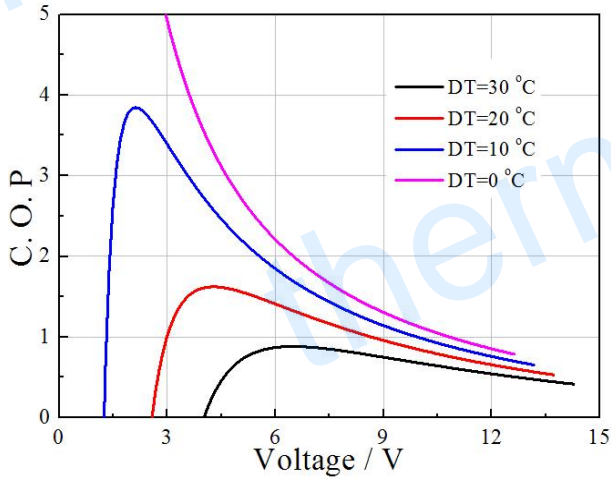


Standard Performance Graph $Q_c = f(V)$

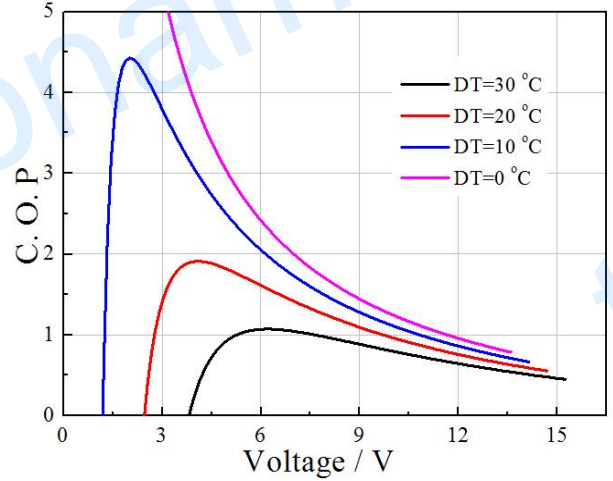
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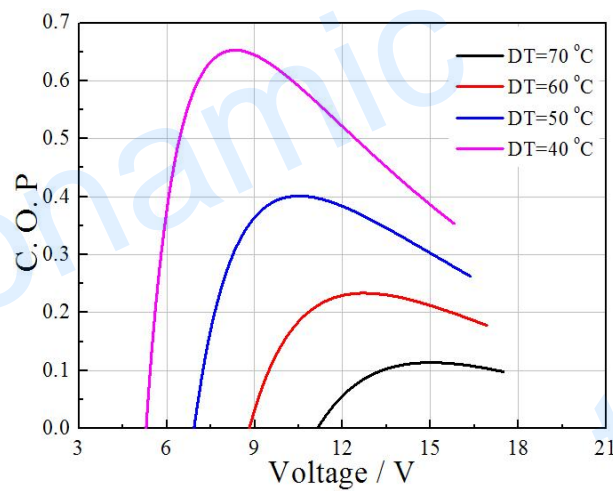
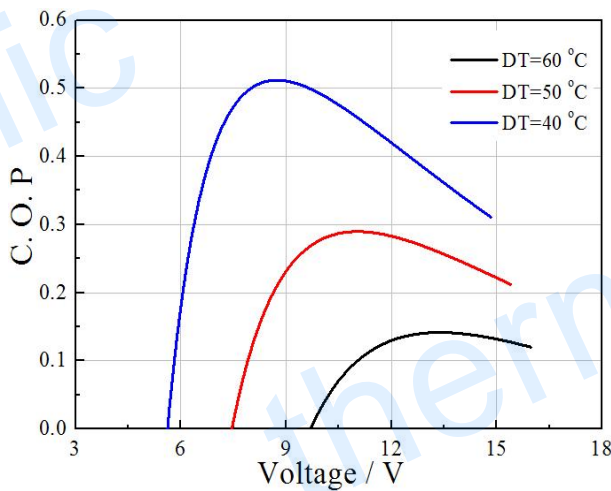
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I_{max} or V_{max}
- Operation or storage module below 100 °C
- Work under DC